



A layer transfer technology revolution – February 6, 2024



Newsletter: 6th February
2024



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FEATURED



The complexities of onshoring chip production amidst geopolitical risks

Recent developments, including the Covid-19 pandemic and catastrophic events like freezes and fires, have shed light on the disruptions caused by chip shortages and related supply chain issues. Moreover, the uncertainty created by rising geopolitical tensions has awakened the sector to impacts that exceed the balance sheet of any one firm. By George Haitzsch, who leads the North American Tech + Media + Telecom Division for WTW.

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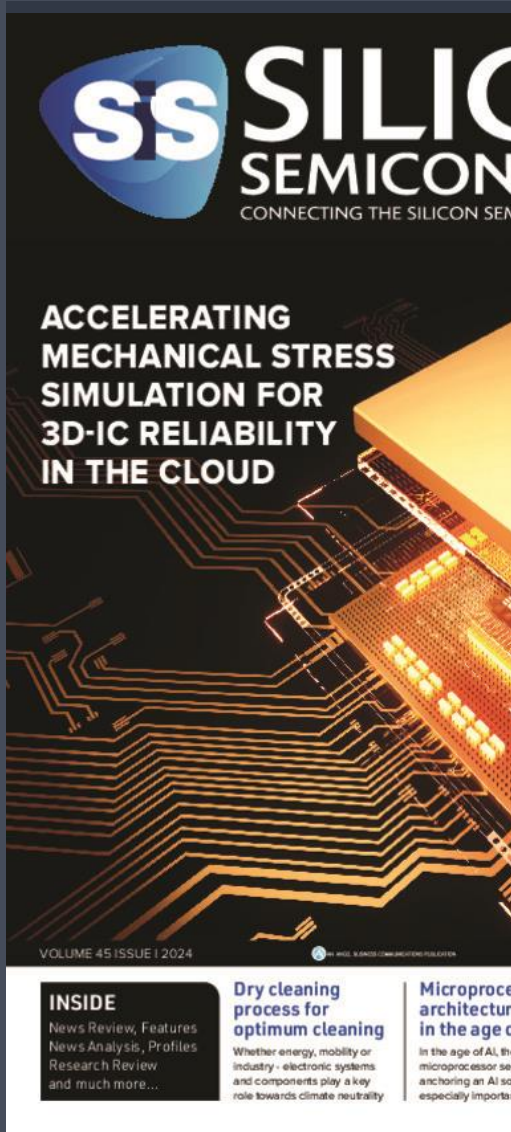
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Filling the metrology void

Nearfield Instruments B.V. recently launched AUDIRA – said to be the industry’s first and only in-line, non-destructive subsurface metrology system for advanced semiconductor manufacturing. By Niranjan Saikumar; Co-authors: Nelda Antonovaitė, Irene Battisti, Taras Piskunov, Mehdi Soozande

INTERVIEWS

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 <p>Jackie Cannon Director of Publishing jackie.cannon@angelbc.com</p>	 <p>Phil Alsop Editor phil.alsop@angelbc.com</p>
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